

SOT1054-1

plastic thermal enhanced very thin small outline package; no leads; 14 terminals; body 3 x 4 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON14
Package type industry code	HVSON14
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	6-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	14	-	

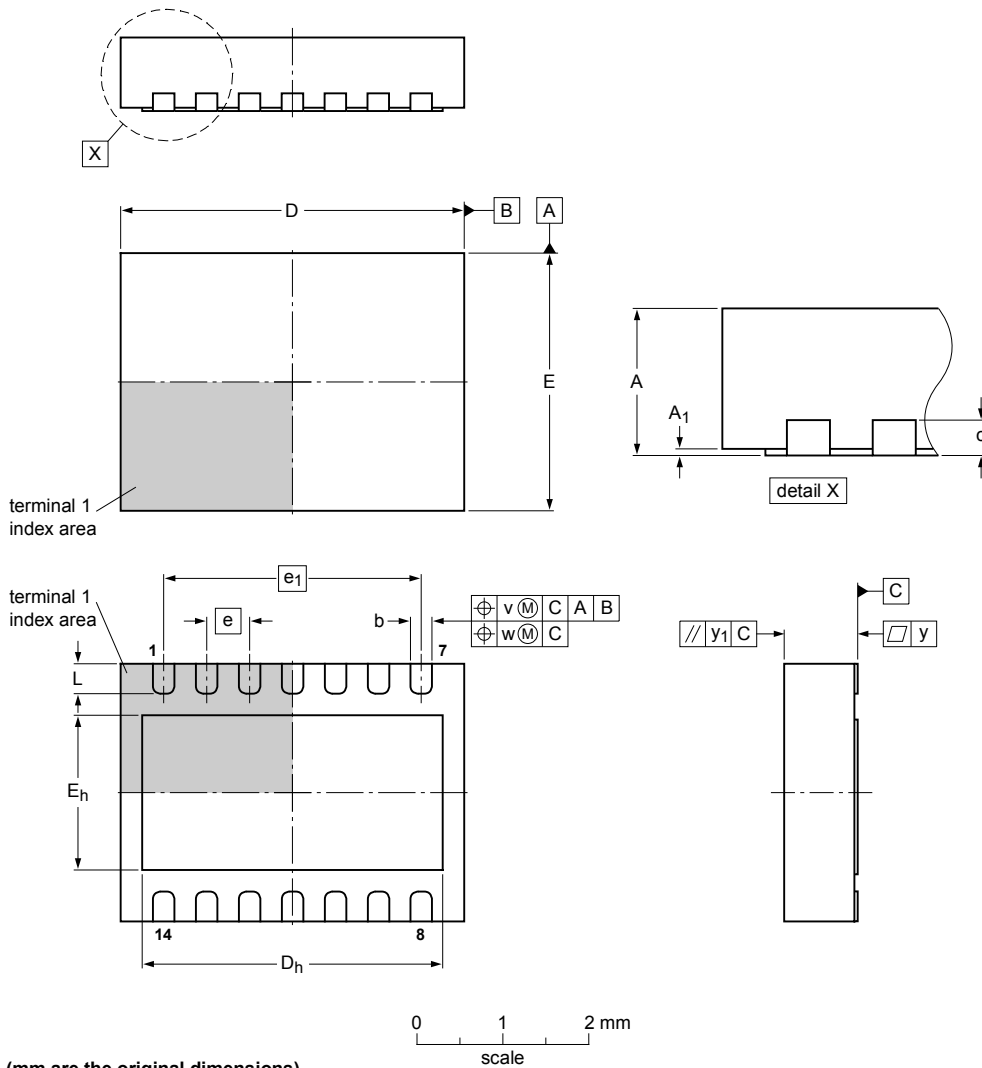


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2. Package outline

HVSON14: plastic thermal enhanced very thin small outline package; no leads; 14 terminals; body 3 x 4 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	L	v	w	y	y ₁
mm	1	0.05 0.00	0.3 0.2	0.2	4.1 3.9	3.6 3.4	3.1 2.9	1.9 1.7	0.5	3	0.4 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1054-1	---	---	---			07-11-23 08-03-06

Fig. 1. Package outline HVSON14 (SOT1054-1)

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3. Soldering

Footprint information for reflow soldering of HVSON14 package

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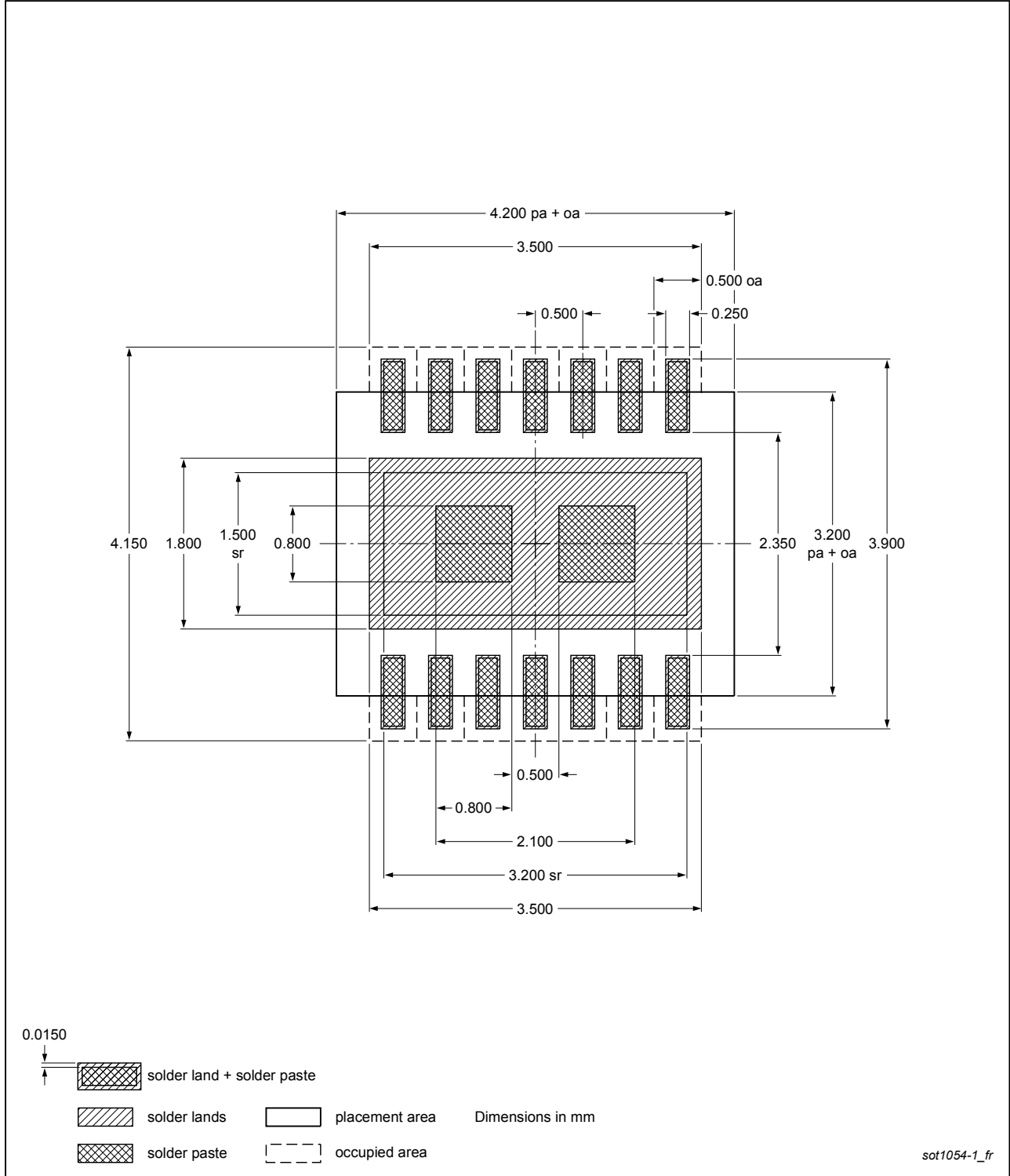


Fig. 2. Reflow soldering footprint for HVSON14 (SOT1054-1)

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4. Legal information

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